

Advanced Program and Registration on-line: www.imaps.org/wirebonding

IMAPS and SEMI Topical Workshop on
Wire Bonding

July 13, 2009

San Francisco Marriott Hotel
San Francisco, California - USA

General Chair:

Mike McKeown, Orthodyne Electronics Corporation
P: 516-739-2690
mike.mckeown@orthodyne.com

Workshop Organizing Committee

Joe Bubel
Hesse & Knipps

Bob Chylak
Kulicke and Soffa Industries, Inc.

Daniel Evans, Jr.
Palomar Technologies, Inc.

Joe Lippincott
Oerlikon ESEC USA Inc.



Advance Registration Ends: June 19, 2009

Hotel Cut-off: June 29, 2009

Wire Bonding Workshop Focus

The objective of the Wire Bonding Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of Wire Bonding. The workshop has been specifically organized to allow for the presentation and debate of leading edge Wire Bonding Technology and Applications.

Monday, July 13, 2009

Registration: 8:30 am - 4:30 pm

Continental Breakfast: 8:30 am - 9:15 am

Opening Remarks: 9:15 am - 9:30 am

SESSION 1: COPPER AND GOLD BALL BONDING

Session Chairs:

Daniel D. Evans, Jr., Palomar Technologies, Inc.;

Joe Bubel, Hesse & Knipps

9:30 am - 12:15 pm

Nickel-Palladium Bond Pads for Copper and Gold Wire Bonding

Horst Clauberg, Asaf Hashmonai, Jamin Ling, Bob Chylak, Kulicke and Soffa Industries, Inc.; Tom Thieme, Atotech GmbH

Wirebonded Gold Inductor on Top of ICs

James J. Wang, Power Gold LLC

HAZ-Free Ultra-Low Loop Method for Multi-Chip Stacked Die Applications

Jovy Michael G. Sena, Marcelino Buenaflor, Ireneo Villavert, Marit Seidel, Oerlikon ESEC USA Inc.

Break: 11:00 am - 11:15 am

Wire Bonding Semiconductor Devices for Metallurgists

Lee R. Levine, Process Solutions Consulting

Inert Environment Requirements for Copper Ball Bonding

Bob Chylak, Shai Friedman, John Foley, Gary Gillotti, Gary Schulze, Kulicke and Soffa Industries, Inc.

SESSION 2: WIRE / RIBBON BONDING & MATERIALS

Session Chair:

Mike McKeown, Orthodyne Electronics Corporation

9:30 am - 12:15 pm

The Stressful World of RF Ribbon Bonding

Joseph J. Kreuzpaintner, Karen Wooldridge, Donna Gerrity, Tom Shenton, Steve Wilson, Jeff Jennings, Harris GCSD

Characterization and Calibration of the Ultrasonic System of U/S Wire and Flip-Chip Die Bonders

Mike Kölling, F&K Physiktechnik GmbH

Wire Bond Integrity Versus Surface Finish of Aluminum Clad Substrates

Barry Njoes, David Williams, Paula Goldstein, Technical Materials Inc.; Mike McKeown, Orthodyne Electronics; Steve Lopez, Farmingdale State College

Break: 11:00 am - 11:15 am

Practical Considerations for PowerRibbon® Bonding of Hybrid Packages

Richard Elliott, Orthodyne Electronics

Perfection Through Inspection: The Way to Zero-Defect Production of Wire Bonds

Josef Sedlmair, F&K Delvotec Bondtechnik GmbH

Lunch: 12:15 pm - 1:15 pm

THANK YOU

A SPECIAL *THANK YOU*

TO ALL OF THE MEMBERS OF THE
ORGANIZING COMMITTEE,
THE CHAIRS AND SPEAKERS.

**YOUR PARTICIPATION
IS
GREATLY APPRECIATED!**

Wire Bonding Speaker Information

Extended Abstract or Presentation Material due: **June 19, 2009**. Send your extended abstract or presentation material via email to jmorris@imaps.org, in PDF format only (PDF can be in color).

Powerpoint/Presentation file used during session: **Speaker's responsibility to bring to session on USB and/or CD** (recommended to have back-up on personal laptop, CD-ROM, or memory stick). Laptops will be provided by IMAPS in the session room.

Speakers must register for the workshop at the reduced speaker rate. Advance registration deadline is June 19, 2009. Visit www.imaps.org/wirebonding for more information.

SESSION 3: COPPER AND GOLD BONDING & MATERIALS

Session Chairs:

Lee Levine, Process Solutions Consulting; Keith Easton, Oerlikon ESEC USA Inc.

1:15 pm - 4:15 pm

Odd Form Factor Package Wire Bonding Case Studies

Daniel D. Evans, Jr., Palomar Technologies, Inc.

Advanced Looping in Copper Wire Bonding

O Dal Kwon, Bob Chylak, Oranna Yauw, Samuel III Capistrano, Kulicke & Soffa Industries, Inc.

Overview of Actual Bonding Wire Technologies and Possible Solutions Based on Different Interconnection Materials

Tobias Mueller, Eugen Milke, Ping Ha Yeung, W. C. Heraeus GmbH

Break: 2:45 pm - 3:15 pm

Copper Wirebonding without the Plasma

Terence Q. Collier, CV Inc.

Bond Wire Yield Rate Optimization on SiP in a 3D Design Environment

John Sovinsky, Gordon Jensen, CAD Design Software

Closing Remarks: 4:15 pm

Mark Your Calendar. You Don't Want to Miss These Upcoming IMAPS Events!!!

International Conference on High Temperature Electronics Network (HiTEN) Oxford, UK

September 13 - 16, 2009

Visit www.imaps.org/hiten for more information.

Advanced Technology Workshop on RF and Microwave Packaging The Crowne Plaza San Diego San Diego, California - USA September 22 - 24, 2009

Visit www.imaps.org/rf for more information.

Advanced Technology Workshop on Thermal Management San Jose/Palo Alto, California - USA October 2009

Visit www.imaps.org/thermal for more information.

42nd International Symposium on Microelectronics (IMAPS 2009)

**San Jose Convention Center
San Jose, California - USA
November 1 - 5, 2009**

Visit www.imaps2009.org for more information.

Topical Workshop and Tabletop Exhibition on Intelligent Uses of Precious Metals in Microelectronics

This event will run immediately following the IMAPS 2009 Symposium - November 1-5.

**San Jose, California - USA
November 5 - 6, 2009**

Visit www.imaps.org/preciousmetals for more information.

REGISTRATION FORM

REGISTER ON-LINE AT WWW.IMAPS.ORG/WIREBONDING
WIRE BONDING WORKSHOP - JULY 13, 2009

Dr. Mr. Ms. IMAPS Member ID# _____
First Name _____ M.I. _____ Last Name _____
Company/Affiliation _____ Job Position _____
Address _____
City _____ State _____ Zip _____ Country _____
Phone _____ Fax _____ Email _____

REGISTRATION FEES: EARLY REGISTRATION ENDS 6/19/09

WORKSHOP FEES

	(On or before 6/19)	(After 6/19)
<input type="checkbox"/> IMAPS Member*	\$375	\$475
<input type="checkbox"/> Non-member*	\$475	\$575
<input type="checkbox"/> Speaker* <input type="checkbox"/> Chair* <input type="checkbox"/> Chapter Officer*	\$275	\$325
<input type="checkbox"/> Student*	\$175	\$225

*Includes one-year IMAPS individual membership or membership renewal at no additional charge. Does not apply to corporate or affiliate memberships. Workshop Fee includes an Abstract book, all meals listed and a CD-ROM of presentations. CD will be mailed 15 business days after the event.

ADDITIONAL PURCHASES

<input type="checkbox"/> Guest/Family Member (meals only)	\$150	\$150
<input type="checkbox"/> CD of Presentations (IMAPS Member Rate)	\$200	\$200
<input type="checkbox"/> CD of Presentations (Non-Member Rate)	\$300	\$300
<input type="checkbox"/> Add to Ship in the US	\$7	\$7
<input type="checkbox"/> Add to Ship Overseas	\$25	\$25

HOUSING

The IMAPS Topical Workshop is being run at the San Francisco Marriott Hotel, in conjunction with SEMICON West.

To book on-line, please visit the official housing site:

https://www.cmrhousing.com/SEMI_S5/HotelList.aspx

Or call the SEMICON West Housing Office

Monday - Friday, 6:00am - 6:00pm; Pacific Standard Time.

1-800-421-2499 (US & Canada)

1-415-979-2287 (International)

Hotel Cut-off is June 29, 2009

San Francisco Marriott Hotel

55 Fourth Street

San Francisco, CA 94103

Single: \$273/night – 1 person Double: \$293/night – 2 persons

Please reference SEMICON West when making reservations by phone.

PAYMENT

WB09

Workshop Fee: \$ _____
Additional Purchases: \$ _____
Total Payment Due: \$ _____

Enclosed is a check payable in US funds to IMAPS

Charge my fees to:

AMEX VISA MC Diners Discover

Card# _____ Exp. _____

Signature _____

Card billing address, if different from above: (required)

Email address required to receive confirmation of registration.

For Wire Transfer information, call 202-548-4001.

Mail this form with payment to: IMAPS * 611 2nd Street, NE * Washington, DC 20002-4909. For credit card transactions, register on-line: www.imaps.org; or register by phone with your credit card by calling 202-548-4001; Fax: 202-548-6115. Additional information? E-mail: IMAPS@imaps.org, or visit our web site: <http://www.imaps.org>. Cancellations will be refunded (less a \$50 processing fee) only if written notice is postmarked on or before **Monday, June 29, 2009**. No refunds will be issued after that date.

IMAPS Registration
611 2nd Street, NE
Washington, DC 20002-4909

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First-Class Mail
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